

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY
CONVEYING PARTY DATA	
Name	Execution Date
Roy Jewell	04/17/2008
RECEIVING PARTY DATA	
Name:	Clarisay, Inc.
Street Address:	2626 Howell Street
Internal Address:	Suite 840
City:	Dallas
State/Country:	TEXAS
Postal Code:	75204
PROPERTY NUMBERS Total: 3	
Property Type	Number
Patent Number:	6734599
Patent Number:	7299528
Application Number:	11986788
CORRESPONDENCE DATA	
Fax Number:	(650)969-8203
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
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Email:	htran@imsciences.com
Correspondent Name:	Hannah Tran
Address Line 1:	650 Castro Street
Address Line 2:	Suite 220
Address Line 4:	Mountain View, CALIFORNIA 94041
NAME OF SUBMITTER:	Hannah Tran

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Total Attachments: 4
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RELEASE OF SECURITY INTEREST

This Release of Security Interest (this "**Release**"), dated as of April 17, 2008, is by Roy Jewell, an individual with mailing address at 919 Ramona St., Palo Alto, CA 94301 ("**Jewell**").

A. Pursuant to a Security Agreement dated as of January 14, 2004, as may have been amended from time to time (the "**Security Agreement**"), Clarisay, Inc., a Delaware corporation ("**Debtor**") granted to Jewell a security interest in all intellectual property assets of Debtor.

B. Jewell is informed that such intellectual property assets of Debtor may include the patents, and patent applications, and related assets, including rights to patents and applications more fully described in Exhibit A to this Release (the "**Patent Rights**").

C. WHEREAS, the Security Agreement was filed with the United States Patent and Trademark Office at the Reel and Frame number below:

<u>Debtor</u>	<u>Secured Party</u>	<u>Reel/Frame</u>	<u>Filing Date</u>
Clarisay, Inc.	Roy Jewell	014546/0393	April 23, 2004

D. WHEREAS, Debtor and Jewell entered into a Mutual Release and Settlement Agreement dated as of August 16, 2006, in which Jewell agrees to release any and all liens against any and all Debtor's and/or the bankruptcy estate of Debtor's assets.

NOW, THEREFORE, FOR VALUE RECEIVED, Jewell does hereby irrevocably and unconditionally release any and all right, title or interest of any kind that exists today and may exist in the future in and to the Patent Rights, including any security interest granted to Jewell under the Security Agreement. Notwithstanding the foregoing, Jewell makes no representation whatsoever with respect to whether or not or to what extent any of the Patent Rights set forth in Exhibit A were, in fact, intellectual property assets of Debtor.

This Release is governed by the law of the State of Delaware, excluding its choice of law principles to the contrary. This Release shall be binding upon Jewell and its successors and assigns and inures to the benefit of any purchaser of the Patent Rights and its successors and assigns.

IN WITNESS WHEREOF, this Release of Security Interest is executed as of the date set forth above.

Roy Jewell

By: Roy Jewell
Name: Roy Jewell
(Signature **MUST** be notarized)

STATE OF California)
COUNTY OF Santa Clara)^{ss.}

On April 17, 2008, before me, Tanya T Nuss, Notary Public in and for said State, personally appeared Roy Jewell, who proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he/she executed the same in his/~~her~~ authorized capacity, and that by his/~~her~~ signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

Signature Tanya T Nuss (Seal)

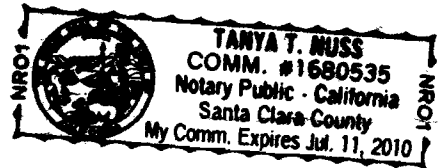


EXHIBIT A

The following describes the “*Patent Rights*” subject to the foregoing Release:

- (a) the patent applications and patents listed in the table below (“*Patents*”):

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
US 6744336	US	10/15/2002	Wafer-scale package for surface acoustic wave circuit and method of manufacturing the same, by Martin Goetz
US 6734599	US	1/05/2001	System and method for dissipating static charge generated in a surface acoustic wave device, James E. Flowers.
US 6650205	US	03/29/2001	Wafer-scale package for surface acoustic wave circuit and method of manufacturing the same, by Martin Goetz
US 6649446	US	11/29/2001	Hermetic package for multiple contact-sensitive electronic devices and methods of manufacturing thereof, by Martin Goetz
US 6639150	US	04/23/2002	Hermetic package for surface acoustic wave device having exposed device substrate contacts and method of manufacturing the same, by Martin Goetz
US 6621379	US	11/29/2001	Hermetic package for surface acoustic wave device and method of manufacturing the same, by Martin Goetz
US 6593678	US	10/24/2000	Surface acoustic wave filter having diminished bandwidth and method of operating the same, by James E. Flowers
US 6580197	US	01/05/2001	System and method for dissipating static charge generated in a surface acoustic wave device, by James E. Flowers
US 6507097	US	11/29/2001	Hermetic package for pyroelectric-sensitive electronic device and method of manufacturing the same, by Martin Goetz
US 6495398	US	01/05/2001	Wafer-scale package for surface acoustic wave circuit and method of manufacturing the same, by Martin Goetz
US 6246148	US	05/14/1999	Surface acoustic wave filters, by James E. Flowers
US 7299528	US	11/05/2002	Method for forming a multi-frequency surface acoustic wave device, David Lee
11/986,788	US	11/26/2007	Method for forming a multi-frequency surface acoustic wave device, David Lee

(b) all patents and patent applications (i) to which any of the Patents directly or indirectly claims priority, (ii) for which any of the Patents directly or indirectly forms a basis for priority, and/or (iii) that directly or indirectly incorporate by reference the Patents or are directly or indirectly incorporated by reference by the Patents;

(c) all reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, requests for continuing examinations, divisions, registrations of any item in any of the foregoing categories (a) and (b);

(d) all non-United States patents, patent applications, and counterparts relating to any item in any of the foregoing categories (a) through (c), including, without limitation, certificates of invention, utility models, industrial design protection, design patent protection, and other governmental grants or issuances;

(e) all items in any of the foregoing in categories (b) through (d), whether or not expressly listed as Patents below and whether or not claims in any of the foregoing have been rejected, withdrawn, cancelled, or the like;

(f) all inventions, invention disclosures, and discoveries described in any item in any of the foregoing categories (a) through (e) and all other rights arising out of such inventions, invention disclosures, and discoveries;

(g) all rights to apply in any or all countries of the world for patents, certificates of invention, utility models, industrial design protections, design patent protections, or other governmental grants or issuances of any type related to any item in any of the foregoing categories (a) through (f), including, without limitation, under the Paris Convention for the Protection of Industrial Property, the International Patent Cooperation Treaty, or any other convention, treaty, agreement, or understanding;

(h) all causes of action (whether known or unknown or whether currently pending, filed, or otherwise) and other enforcement rights under, or on account of, any of the Patents and/or any item in any of the foregoing categories (b) through (g), including, without limitation, all causes of action and other enforcement rights for

- (i) damages,
- (ii) injunctive relief, and
- (iii) any other remedies of any kind

for past, current, and future infringement; and

(i) all rights to collect royalties and other payments under or on account of any of the Patents and/or any item in any of the foregoing categories (b) through (h).